

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A light emitting diode package comprising:

a ceramic substrate for mounting a light emitting diode, said substrate defining a cavity with a ceramic sidewall, a ceramic cavity comprising an integrated substrate for mounting a light emitting diode wherein said ceramic cavity and said integrated substrate can be manufactured simultaneously and wherein said cavity is shaped to focus light in a predetermined direction; and

a metallic coating on a portion of said ceramic substrate for reflecting light in a predetermined direction.

2. (Currently Amended) The light emitting diode package as recited in Claim 1 wherein said cavity is substantially a rectangular shaped cavity.

3. (Currently Amended) The light emitting diode package as recited in Claim 1 wherein said cavity is substantially a trapezoidal shaped cavity.

4. (Currently Amended) The light emitting diode package as recited in Claim 1 wherein said cavity is substantially an oval shaped cavity.

5. (Currently Amended) The light emitting diode package as recited in Claim 1 wherein said cavity is substantially a circular shaped cavity.

6. (Cancelled)

7. (Cancelled)

8. (Currently Amended) A method for manufacture of a light emitting diode package comprising:

forming a ceramic substrate for mounting a light emitting diode, said substrate defining a cavity with a ceramic sidewall, and said cavity having a bottom and a top, forming a ceramic cavity having a bottom and a top and comprising an integrated substrate for mounting a light emitting diode wherein said cavity is shaped to focus light in a predetermined direction;

coating a portion of said ceramic cavity with a light reflective material;
positioning a light emitting diode on said substrate; and
depositing an optically transparent material in said cavity to protect said light emitting diode.

9. (Currently Amended) The method as recited in Claim 8 wherein said forming said ceramic substrate ~~said ceramic cavity~~ comprises forming a cavity that is substantially rectangular shaped.

10. (Currently Amended) The method as recited in Claim 8 wherein said forming said ceramic substrate ~~said ceramic cavity~~ comprises forming a cavity that is substantially trapezoidal shaped.

11. (Currently Amended) The method as recited in Claim 8 wherein said forming said ceramic substrate ~~said ceramic cavity~~ comprises forming a cavity that is substantially oval shaped.

12. (Currently Amended) The method as recited in Claim 8 wherein said forming said ceramic substrate ~~said ceramic cavity~~ comprises forming a cavity that is substantially circular shaped.

13. (Cancelled)

14. (Cancelled)

15. (Original) The method as recited in Claim 8 wherein said positioning said light emitting diode comprises determining a location between said bottom and said top of said cavity to locate said light emitting diode to achieve a predetermined viewing angle of said light emitting diode.

16. (Original) The method as recited in Claim 15 further comprising locating said light emitting diode closer to said bottom of said cavity to reduce said viewing angle of said light emitting diode.

17. (Original) The method as recited in Claim 15 further comprising locating said light emitting diode closer to said top of said cavity to increase said viewing angle of said light emitting diode.

18. (Original) The method as recited in Claim 8 wherein said depositing said optically transparent material in said cavity to protect said light emitting diode comprises forming a domed layer of said optically transparent material over said light emitting diode.

19. (Original) The method as recited in Claim 8 wherein said depositing said optically transparent material in said cavity to protect said light emitting diode comprises forming a concaved layer of said optically transparent material over said light emitting diode.

20. (New) The light emitting diode package of Claim 1, wherein said ceramic sidewall is vertical.

21. (New) The method as recited in Claim 8, wherein said ceramic sidewall is vertical.